L Number	Hits	Search Text	DB	Time stamp
1	1958322	wafer wafers substrate substrates	USPAT;	2004/03/30 08:09
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
2	332811	stainless add steel	_	0004/02/20 00 00
4	332011	stainless adj steel	USPAT;	2004/03/30 08:09
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
3	2125	ivar	USPAT;	2004/03/30 08:09
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
4	8649	noliching with /table compant)		0004/00/00 00 00
4	0049	polishing with (table support)	USPAT;	2004/03/30 08:09
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	.
			IBM TDB	
5	88	(wafer wafers substrate substrates) same	USPAT;	2004/03/30 08:22
		(polishing with (table support)) same	US-PGPUB;	
		((stainless adj steel) ivar)	EPO; JPO;	
1		,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,,	DERWENT;	
1			1	
6	3616	work adj holder	IBM_TDB USPAT;	2004/03/30 00:00
ا	2010	work adj norder .		2004/03/30 08:22
			US-PGPUB;	
			EPO; JPO;	
		-	DERWENT;	
			IBM_TDB	
7	1044944	carrier	USPAT;	2004/03/30 08:22
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
8	2723491	plate	USPAT;	2004/03/30 08:22
		, p	US-PGPUB;	2004/05/50 00.22
1			EPO; JPO;	
			DERWENT;	
9	3560663	(IBM_TDB	
	3360663	(work adj holder) carrier plate	USPAT;	2004/03/30 08:22
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
l			IBM_TDB	
10	72000	silicon adj carbide	USPĀT;	2004/03/30 08:22
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
11	66222	"SiC"	USPĀT;	2004/03/30 08:22
			US-PGPUB;	= 30 1, 00, 00 00 . 22
	l		EPO; JPO;	
]				
			DERWENT;	
12	110001	(ailian add cowhide Maigu	IBM_TDB	2004/02/20 22 22
12	118961	(silicon adj carbide) "SiC"	USPAT;	2004/03/30 08:22
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	!
1			IBM_TDB	
13	6535	((work adj holder) carrier plate) with	USPĀT;	2004/03/30 08:30
		((silicon adj carbide) "SiC")	US-PGPUB;	
			EPO; JPO;	1
	' I		DERWENT;	I
1			IBM TDB	j
14	1201	(((work adj holder) carrier plate) with	USPAT;	2004/03/30 08:23
1 1	1201	((silicon adj carbide) "SiC")) with (wafer	US-PGPUB;	2004/03/30 08:23
	l	wafers substrate substrates)		1
		waters sanstrate sanstrates)	EPO; JPO;	1
1			DERWENT;	1
			IBM TDB	

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16	F01000	Turni di li	LUCDAM	2004/02/20 00 02
15	501920	ribs recesses	USPAT; US-PGPUB;	2004/03/30 08:23
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
16	7	((((work adj holder) carrier plate) with	USPAT;	2004/03/30 08:25
"		((silicon adj carbide) "SiC")) with (wafer	US-PGPUB;	2001,03,30 00120
		wafers substrate substrates)) with (ribs	EPO; JPO;	
		recesses)	DERWENT;	
	İ		IBM TDB	
17	8	((((work adj holder) carrier plate) with	USPĀT;	2004/03/30 08:24
		((silicon adj carbide) "SiC")) with (wafer	US-PGPUB;	
		wafers substrate substrates)) same (ribs	EPO; JPO;	
		recesses)	DERWENT;	
	İ		IBM_TDB	
18	1	(((((work adj holder) carrier plate) with	USPAT;	2004/03/30 08:24
		((silicon adj carbide) "SiC")) with (wafer	US-PGPUB;	
		wafers substrate substrates)) same (ribs	EPO; JPO;	
		recesses)) not (((((work adj holder) carrier plate) with ((silicon adj carbide)	DERWENT; IBM TDB	
		"SiC")) with (wafer wafers substrate	1564_155	
		substrates)) with (ribs recesses))		
19	8		USPAT;	2004/03/30 08:26
	_	((silicon adj carbide) "SiC")) with (wafer	US-PGPUB;	
		wafers substrate substrates)) same (ribs	EPO; JPO;	
		recesses)	DERWENT;	
			IBM_TDB	
20	60		USPAT;	2004/03/30 08:26
		((silicon adj carbide) "SiC")) with (wafer	US-PGPUB;	
		wafers substrate substrates)) and (ribs	EPO; JPO;	
		recesses)	DERWENT;	
21	52	(((((work adj holder) carrier plate) with	IBM_TDB USPAT;	2004/03/30 08:26
21	, ,,,	((silicon adj carbide) "SiC")) with (wafer	US-PGPUB;	2004/03/30 08.20
		wafers substrate substrates)) and (ribs	EPO; JPO;	
		recesses)) not ((((work adj holder)	DERWENT;	
		carrier plate) with ((silicon adj carbide)	IBM TDB	
		"SiC")) with (wafer wafers substrate	_	
		substrates)) same (ribs recesses))		
22	1		USPAT;	2004/03/30 08:34
		((silicon adj carbide) "SiC") same (ribs	US-PGPUB;	
		recesses) same ((rear back) adj (surface	EPO; JPO;	
		face))	DERWENT;	
23	1254	451/398	<pre>IBM_TDB USPAT;</pre>	2004/03/30 08:34
23	1254	101/000	US-PGPUB;	2004/03/30 00:34
			EPO; JPO;	
			DERWENT;	
			IBM TDB	
24	947	451/398.ccls.	USPAT;	2004/03/30 08:34
			US-PGPUB;	
			EPO; JPO;	
			DERWENT;	
			IBM_TDB	
25	14	',	USPAT;	2004/03/30 08:34
		451/398.ccls.	US-PGPUB;	
			EPO; JPO;	
			DERWENT; IBM TDB	
	11		TOM TOD	L_,